ABSTRACT OF THE DISCLOSURE

A light emitting diode (LED) module illuminates under application of an electrical current for use in an electrical device as a light source. The LED module includes a plurality of epitaxy chips, an electrode set, and a substrate having good electrical insulation and good heat dissipation. The epitaxy chips, formed by cutting an epitaxy wafer, are mounted on the substrate. The LED module has good heat dissipation properties, thereby improving its illumination performance. The electrodes are arranged so that the illuminating area of the LED module is not shielded and can achieve full-area illumination through a large illumination area.